



TO263

1、封装结构:

TO263 封装, 通常包含 2 个主要引脚 (如漏极、源极) 和 1 个辅助引脚 (如栅极), 部分型号可能有更多引脚配置。其特点是采用表面贴装设计, 底部有较大的散热焊盘, 可通过 PCB 实现散热, 适用于高功率应用场景。

1. Package Structure

The TO263 package typically includes 2 main pins (e.g., drain and source) and 1 auxiliary pin (e.g., gate), with some models possibly featuring more pin configurations. It is characterized by a surface-mount design and a large thermal pad on the bottom, which enables heat dissipation through the PCB, making it suitable for high-power applications.

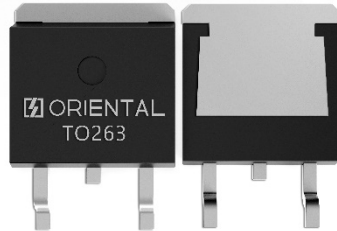


2、尺寸与散热性能:

封装尺寸较大, 相比 TO252 等封装, 能提供更好的散热能力, 适合处理较高功率的电流和电压。

2. Dimensions and Thermal Performance

The package features a relatively large form factor. Compared with packages such as TO252, it delivers superior heat dissipation capability, making it suitable for handling high-power currents and voltages.



3、应用场景：

常用于工业电源、电动汽车控制、高功率电机驱动、太阳能逆变器、服务器电源等对功率和散热要求较高的领域。

3. Application Scenarios

It is commonly used in fields with high requirements for power and heat dissipation, such as industrial power supplies, electric vehicle controls, high-power motor drives, solar inverters, and server power supplies.